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Descrizione fisica	1 online resource (281 p.)
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Soggetti	Microelectronic packaging Electronic books.
Lingua di pubblicazione	Inglese
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Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	Introduction -- Materials -- Ceramic packaging -- Laminate packaging -- First-level interconnects -- Second-level interconnects -- Modules and motherboards -- Transitions and 3D packaging -- Heat transfer -- Electromagnetic modeling -- Conclusions and future horizons.
Sommario/riassunto	Presenting the packaging issues which are unique to microwave and millimeter-wave frequencies, this book reviews lower frequency packaging techniques and how they can be tailored or analyzed for higher frequency designs. --